

DESCRIPTION

The SPN7002L is the N-Channel enhancement mode field effect transistors are produced using high cell density DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 300mA DC and can deliver pulsed currents up to 0.8A. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

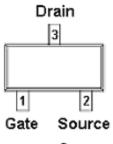
APPLICATIONS

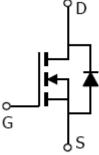
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- High saturation current capability. Direct Logic-Level Interface: TTL/CMOS
- Battery Operated Systems
- Solid-State Relays

FEATURES

- 50V/0.30A, RDS(ON)= $3.5\Omega@VGS=10V$
- 50V/0.25A, RDS(ON)= $5.5\Omega@VGS=4.5V$
- 50V/0.05A, RDS(ON)= 7.5Ω @VGS=2.5V
- ◆ Super high density cell design for extremely low RDS(ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ SOT-23 package design

PIN CONFIGURATION(SOT-23)





PART MARKING



Y : Year Code W : Week Code

PIN DESCRIPTION					
Pin	Symbol	Description			
1	G	Gate			
2	S	Source			
3	D	Drain			

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN7002LS23RGB	SOT-23	L72

% Week Code : A ~ Z(1 ~ 26); a ~ z(27 ~ 52)

※ SPN7002LS23RGB: Tape Reel; Pb − Free; Halogen − Free

ABSOULTE MAXIMUM RATINGS (Ta=25°C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		VDSS	50	V
Gate –Source Voltage - Continuous		VGSS	±20	V
Gate –Source Voltage - Non Repetitive (t _p < 50μs)		VGSS	±40	V
Continuous Drain Current(TJ=150°C)	Ta=25°C	ID	0.3	A
Pulsed Drain Current (*)		Ірм	0.8	A
Power Dissipation	Ta=25°C	PD	0.35	W
Operating Junction Temperature		Тл	-55 ~ 150	°C
Storage Temperature Range		Tstg	-55 ~ 150	°C
Thermal Resistance-Junction to Ambient		RθJA	375	°C/W

(*) Pulse width limited by safe operating area

Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit
	Бушьог	Conditions	141111.	Тур	wa.	Cint
Static						
Drain-Source Breakdown Voltage	V(BR)DSS	Vgs=0V,Id=250uA	50			V
Gate Threshold Voltage	V _{GS(th)}	VDS=VGS,ID=250uA	0.8	1.25	1.5	
Gate Leakage Current	Igss	VDS=0V,VGS=±20V			±100	nA
Zero Gate Voltage Drain Current		V _{DS} =45V,V _{GS} =0V			1	uA
	IDSS	V _{DS} =45V,V _{GS} =0V T _J =125°C			10	
Drain-Source On-Resistance		Vgs=10V,Id=0.30A		2.5	3.5	
	RDS(on)	$V_{GS} = 4.5V, I_{D} = 0.25A$		3.3	5.5	Ω
		$V_{GS} = 2.5V, I_{D} = 0.05A$		5.0	7.5	
Source-drain Current	ISD				0.35	A
Source-drain Current (pulsed)	ISDM (2)	** 40** * 0.7.		0.5	1.4	A
Forward Transconductance	Gfs(1)	$V_{DS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$		0.6		S
Diode Forward Voltage	VsD(1)	$V_{GS} = 0 V, I_{S} = 0.12A$		0.85	1.5	V
Dynamic						
Total Gate Charge	Qg	$V_{DD} = 30 \text{ V}, \text{ ID} = 1 \text{ A},$ $V_{GS} = 5 \text{ V}$		1.4	2.0	nC
Gate-Source Charge	Qgs			0.8		
Gate-Drain Charge	Qgd			0.5		
Input Capacitance	Ciss			43		pF
Output Capacitance	Coss	$V_{DS} = 25 \text{ V, } f = 1 \text{ MHz,}$ $V_{GS} = 0$		20		
Reverse Transfer Capacitance	Crss			6		
Turn-On Time	td(on)	V _{DD} = 30 V, I _D = 0.5 A		5		
	tr			15		
Turn-Off Time	td(off)	$R_G = 4.7\Omega \text{ V}_{GS} = 4.5 \text{ V}$		7		nS
	tf			8		

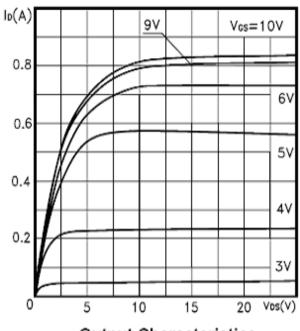
⁽¹⁾ Pulsed: Pulse duration = $300 \mu s$, duty cycle 1.5 %.

⁽²⁾ Pulse width limited by safe operating area.

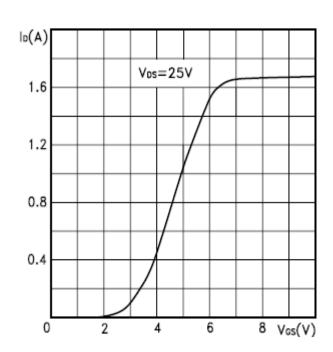


N-Channel Enhancement Mode MOSFET

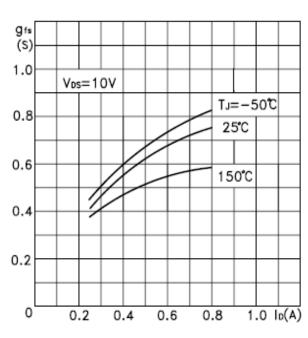
TYPICAL CHARACTERISTICS



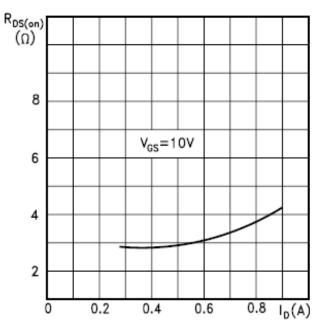
Output Characteristics



Transfer Characteristics



Transconductance

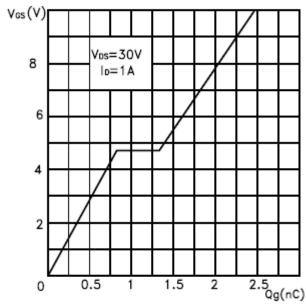


Static Drain-source On Resistance

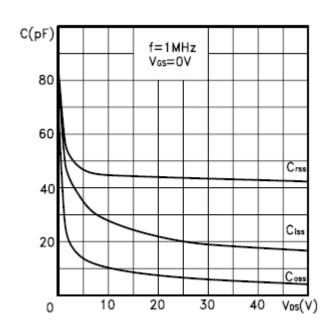


N-Channel Enhancement Mode MOSFET

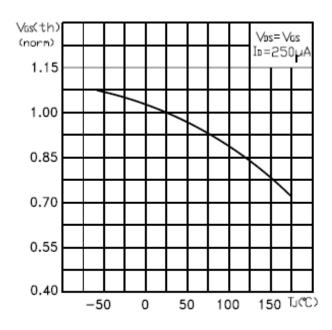
TYPICAL CHARACTERISTICS



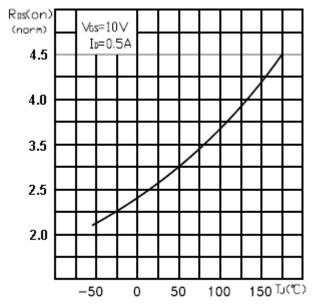
Gate Charge vs Gate-source Voltage



Capacitance Variations



Normalized Gate Threshold Voltage vs Temperature

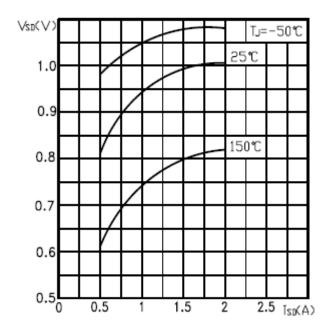


Normalized On Resistance vs Temperature

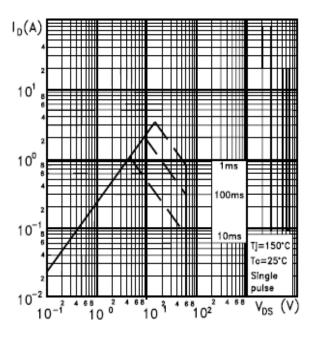


N-Channel Enhancement Mode MOSFET

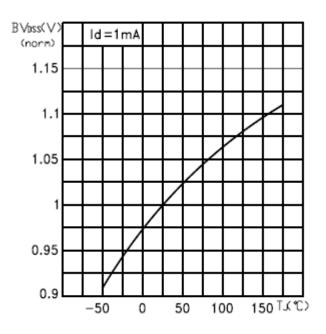
TYPICAL CHARACTERISTICS



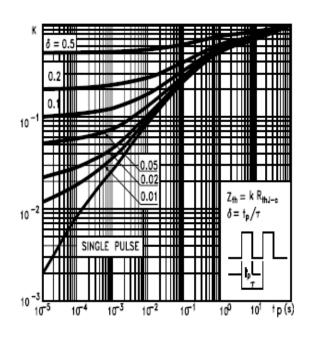
Source-Drain Forward



Safe Operating Area



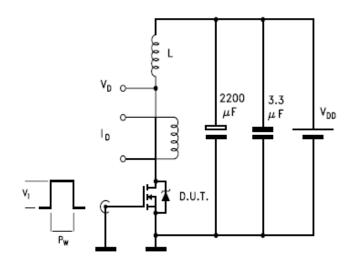
Normalized BVDSS vs Temperature



Thermal Impedance

2020/1/16 Ver.3

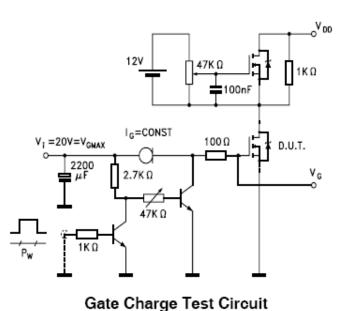
TYPICAL TESTING CIRCUIT

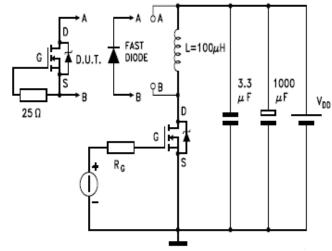


R_L 2200 3.3 μF V_{DD} V_{SS} R_G D.U.T.

Unclamped Inductive Load Test

Switching Times Test Circuit





Test Circuit For Inductive Load Switching and Diode Recovery Times

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